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United States Patent [19]

Hikita

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[54] TAPE MOUNTED HEATSINK PACKAGE FOR ELECTRONIC PARTS

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[73] Assignee: Kyoshin Kogyo Co., Ltd., Tokyo, Japan

[**] Term: 14 Years

[21] Appl. No.: 29/080,599

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[30] Foreign Application Priority Data

Jun. 10, 1997 [JP] Japan 9-57416

[51] LOC (6) Cl. 13-03

[52] U.S. Cl. D13/179

[58] Field of Search D13/179; 174/15.1, 174/16.3; 165/80.3, 185

[56] References Cited

U.S. PATENT DOCUMENTS

D. 301,334	5/1989	Dupasquier et al.	D13/179
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Primary Examiner—Brian N. Vinson

[57] CLAIM

The ornamental design for a tape mounted heatsink package for electronic parts, as shown and described.

DESCRIPTION

FIG. 1 is a top plan view of a tape mounted heatsink package for electronic parts showing my new design; FIG. 2 is a front elevational view thereof; FIG. 3 is a bottom plan view thereof; FIG. 4 is a rear elevational view thereof; FIG. 5 is a left side elevational view thereof, the right side elevational view being mirror image; FIG. 6 is a sectional view thereof, taken along line 6—6 in FIG. 2; and, FIG. 7 is a top, front, and left side perspective view thereof, showing a pair of the heatsinks detached from the tape strip and mounted on an electronic circuit board assembly shown in broken-lines to indicate that it is not intended to form part of the claimed design.

The claimed design is shown broken-away in the views to indicate indeterminate length, it being understood that the heat sink elements are continuous throughout the entire length of the packaging.

1 Claim, 4 Drawing Sheets

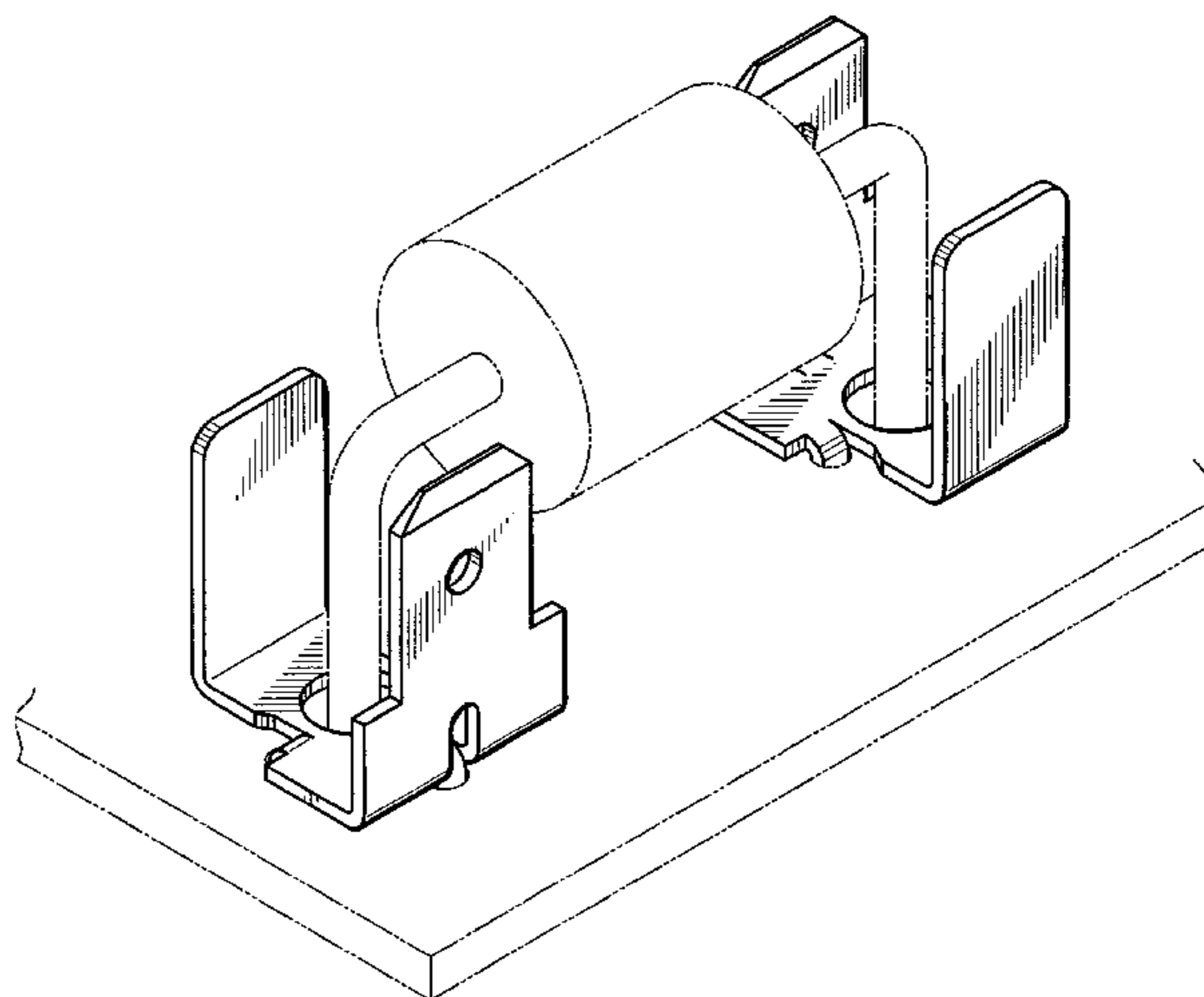
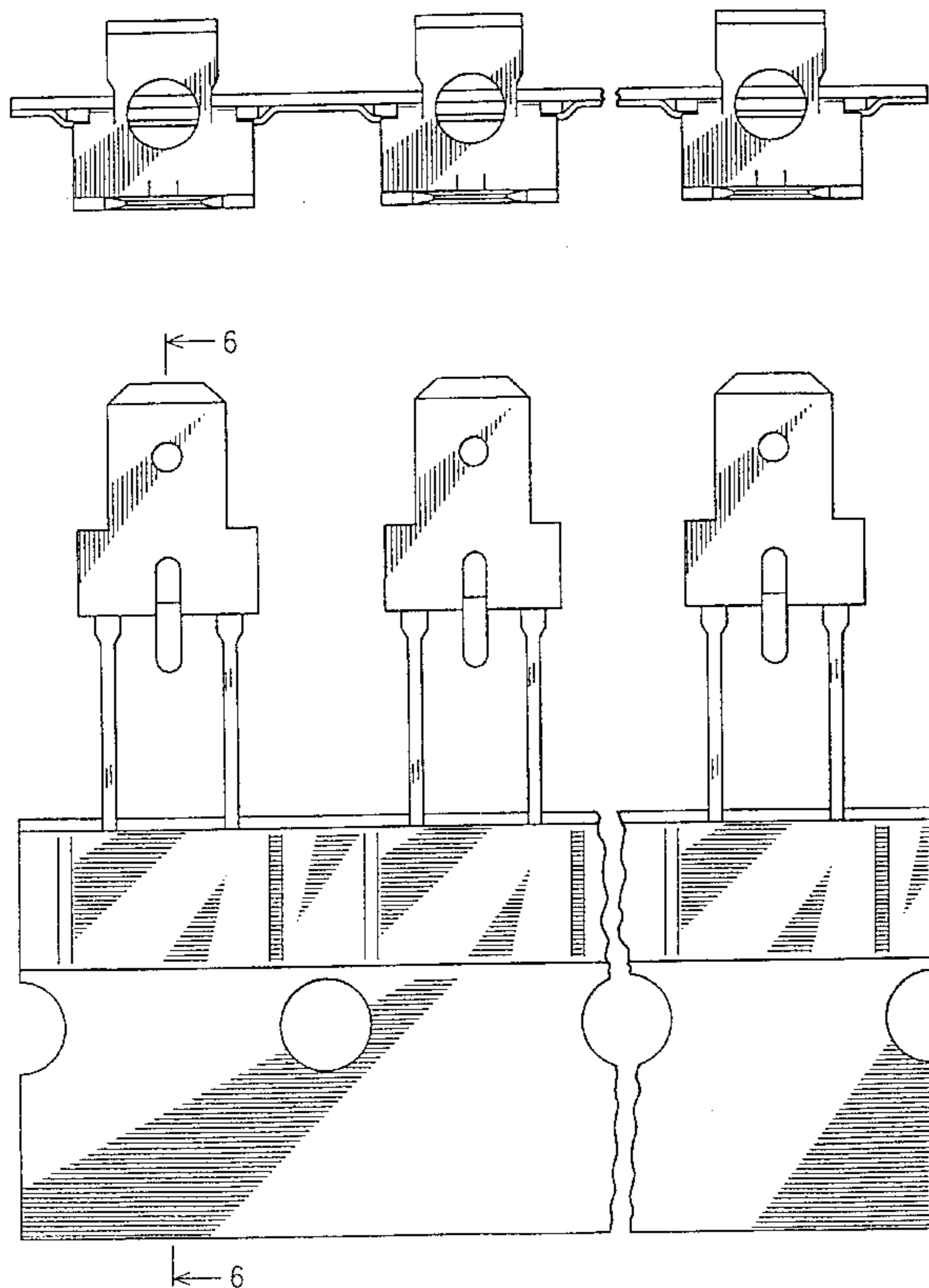


FIG. 1

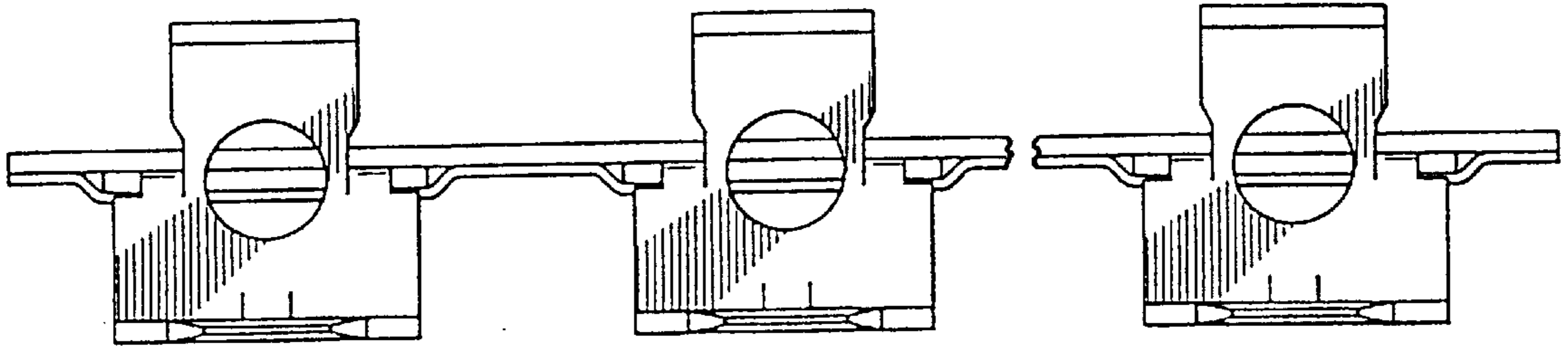


FIG. 2

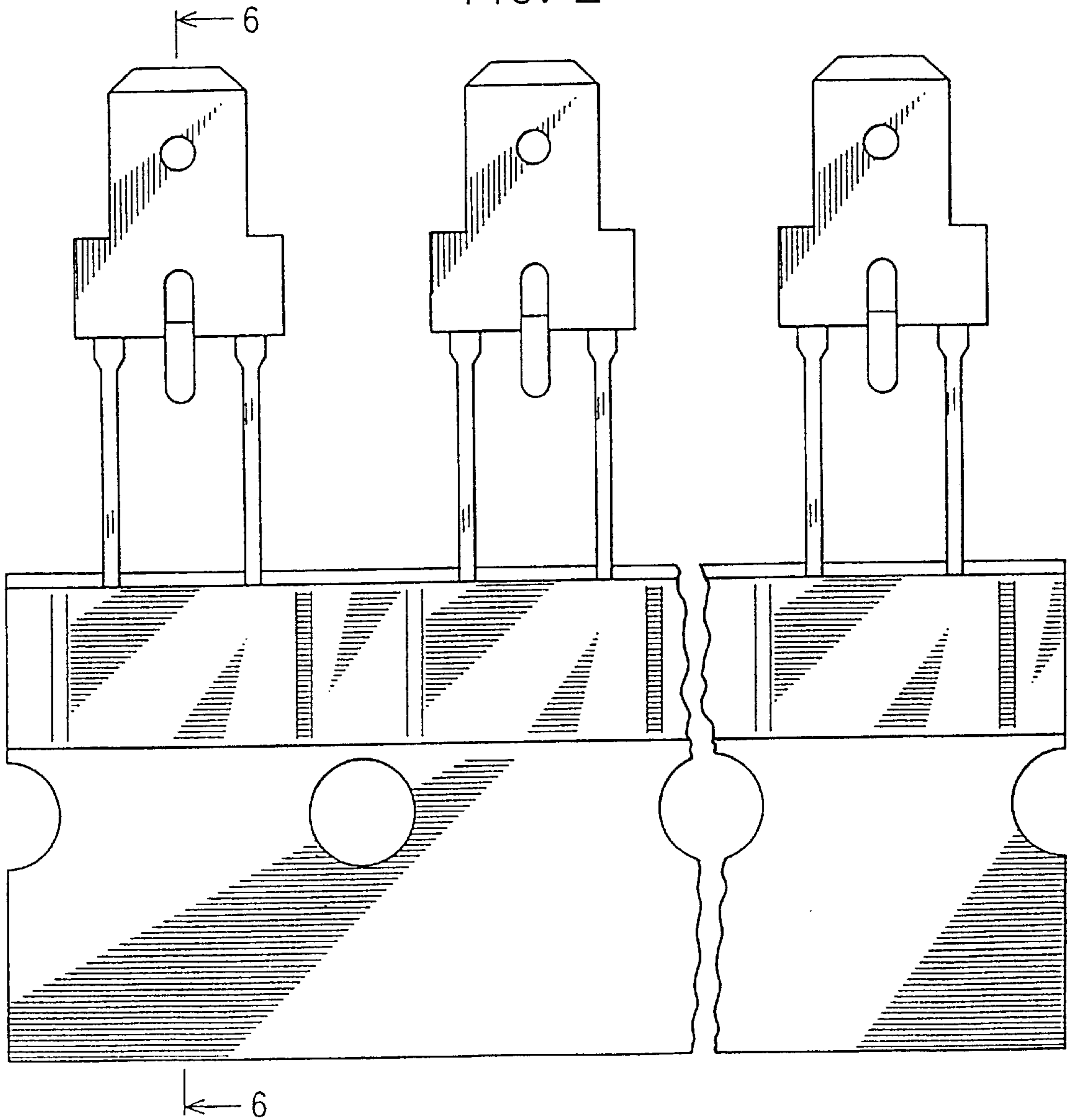


FIG. 3

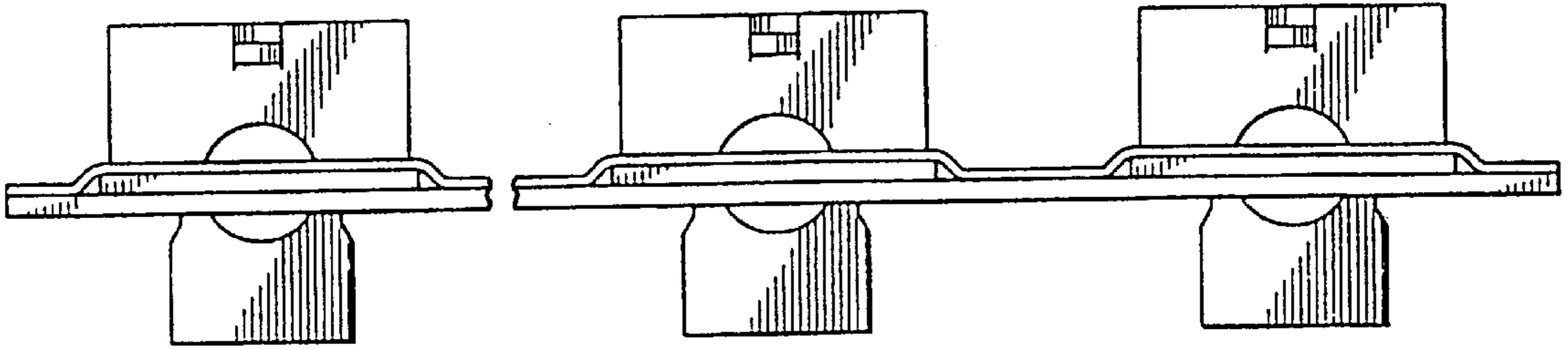


FIG. 4

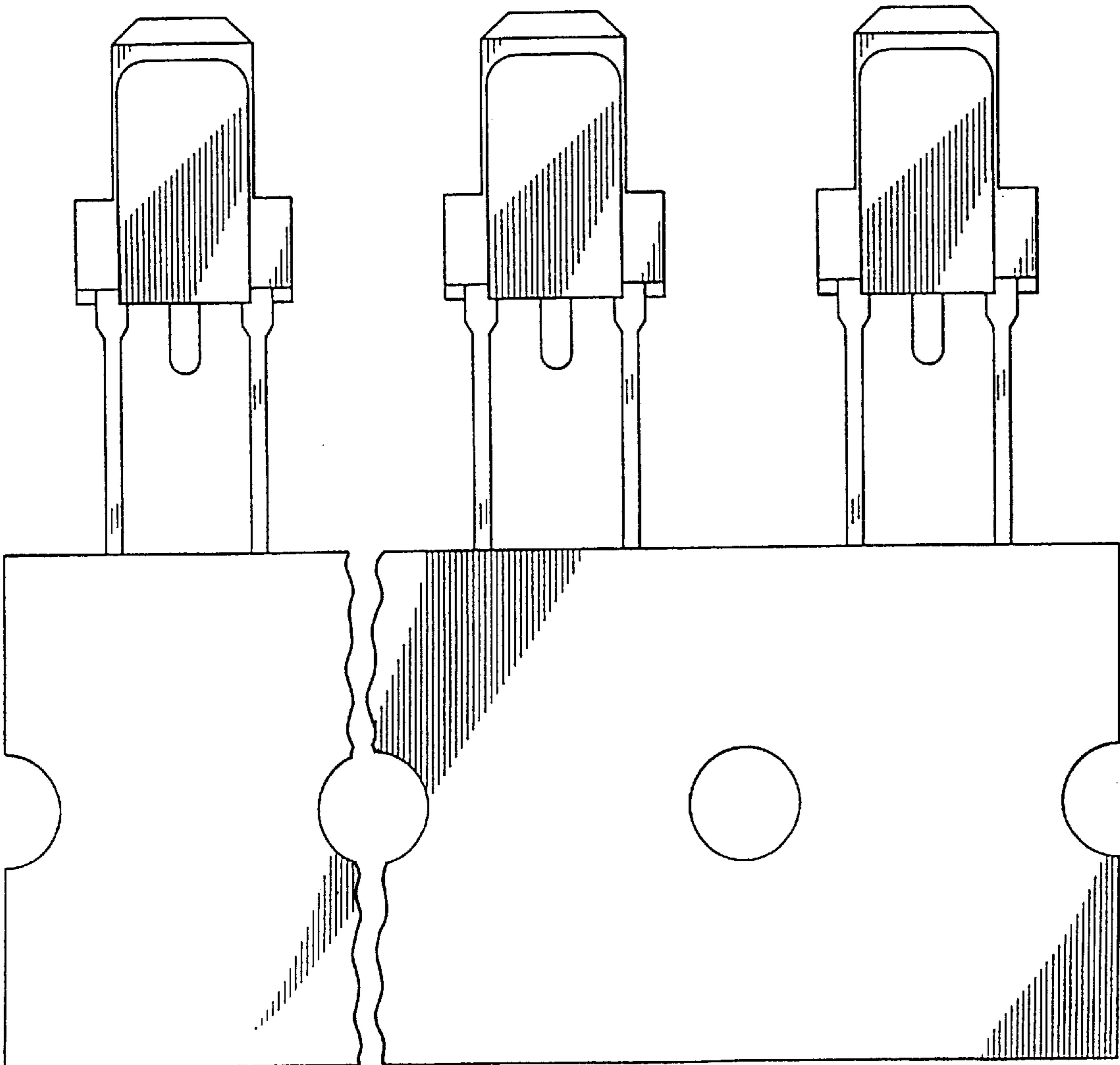


FIG. 5

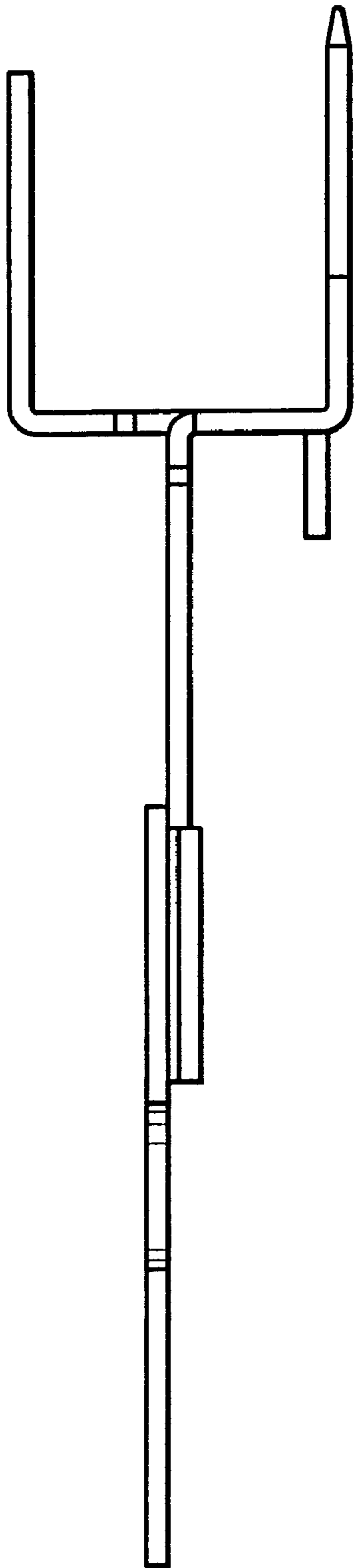


FIG. 6

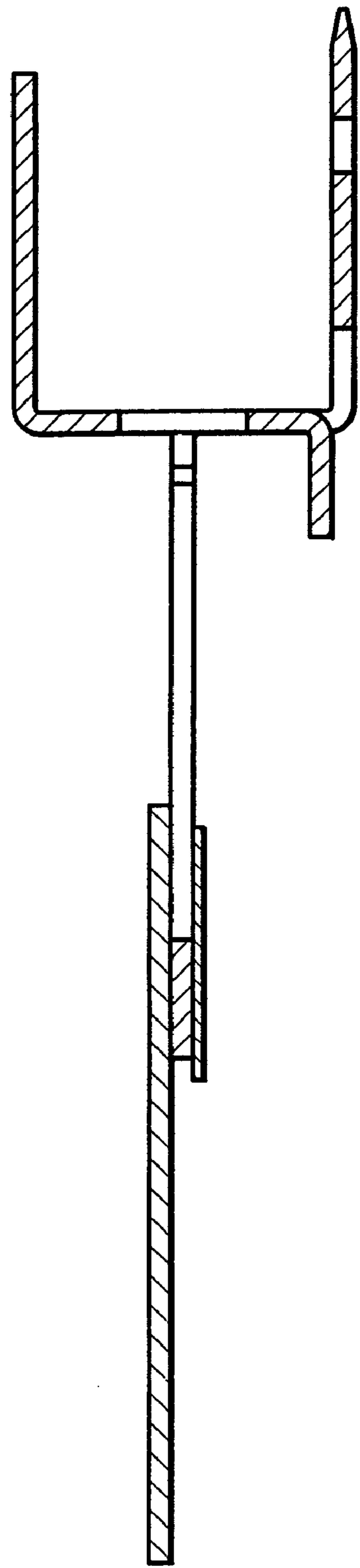


FIG. 7

